ABSTRACT

PROCESS FOR CLEANING WAFERS

[Summary]

[Problem] To provide a washing method for improving washing processes in which pattern destruction is easily induced in manufacturing methods for wafers having concavoconvex patterns on the surface thereof.

[Solution] This washing method for a wafer having a concavoconvex pattern on the surface has at least a step for washing a wafer (1) with a washing fluid (8), a step for replacing the washing fluid (8) that is held in concave parts (4) of the wafer (1) after washing with a water-repellant chemical solution (9), and a step for drying the wafer (1). The washing fluid (8) contains 80% by mass or more of a solvent that has a boiling point of 55 · 200°C. By setting the temperature of the water-repellent chemical solution (9) supplied in the step for replacement to 40°C or more and less than the boiling point of the water-repellent chemical solution (9), at least the surfaces of the concave parts are made water-repellent.

FIG. 4